### Purpose:
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>Screw driver</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. remove SD dummy card
2. remove battery module
3. remove bottom door
4. remove HDD module
5. remove mini card module (Wlan / Wwan)
6. remove K/B modul
7. remove APP board
8. remove Logic_UP assy
9. remove M/B
10. remove USB board
11. remove power board
12. remove display module
13. divide Logic_low assy (remove speaker module)
14. divide Logic_up assy (remove FPR bracket)
15. divide Logic_up assy (remove FPR module)
16. divide Logic_up assy (remove T/P button module)
17. divide M/B (remove thermal module)
18. divide Display assy (remove lcd_bezel)
19. divide Display assy (remove display Hinge)
20. divide Display assy (remove panel module)
21. divide Display assy (remove webcaml module)
22. divide Display assy (remove mic cable module)
23. divide Display assy (remove WWAN cable module)
24. divide Display assy (remove WLAN cable module)
25. divide Display assy (remove LVDS cable)
26. divide M/B assy (remove RTC battery)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Step 1: Remove SD dummy card

Step 2: Remove Battery module

Step 3: Remove Bottom door

Step 4: Remove HDD module
Step 5 : Remove Mini card module (WLAN / WWAN)

Step 6 : Remove K/B module

Step 7 : Remove APP board

Step 8 : Remove Logic_UP assy

Step 9 : Remove MB

Step 10 : Remove USB board
Step 11: Remove power board

Step 12: Remove display module

Step 13: divide Logic_low assy
          (remove speaker module)

Step 14: divide Logic_up assy
          (remove FPR bracket)

Step 15: divide Logic_up assy
          (remove FPR module)

Step 16: divide Logic_up assy
          (remove T/P button module)
Step 17: divide M/B assy  
(remove thermal module)

Step 18: divide Display assy  
(remove LCD_Bezel)

Step 19: divide Display assy  
(remove Display Hinge)

Step 20: divide Display assy  
(remove Panel module)

Step 21: divide Display assy  
(remove Webcam module)

Step 22: divide Display assy  
(remove Mic cable module)
Step 23: divide Display assy (remove WWAN cable module)

Step 24: divide Display assy (remove WLAN cable module)

Step 25: divide Display assy (remove LVDS cable)

Step 26: divide M/B assy (remove RTC battery)